# 8-Stage Shift/Store Register with Three-State Outputs

The MC14094B combines an 8-stage shift register with a data latch for each stage and a 3-state output from each latch.

Data is shifted on the positive clock transition and is shifted from the seventh stage to two serial outputs. The  $Q_S$  output data is for use in high-speed cascaded systems. The  $Q_S$  output data is shifted on the following negative clock transition for use in low-speed cascaded systems.

Data from each stage of the shift register is latched on the negative transition of the strobe input. Data propagates through the latch while strobe is high.

Outputs of the eight data latches are controlled by 3-state buffers which are placed in the high-impedance state by a logic Low on Output Enable.

#### **Features**

- 3-State Outputs
- Capable of Driving Two Low-Power TTL Loads or One Low-Power Schottky TTL Load Over the Rated Temperature Range
- Input Diode Protection
- Data Latch
- Dual Outputs for Data Out on Both Positive and Negative Clock Transitions
- Useful for Serial-to-Parallel Data Conversion
- Pin-for-Pin Compatible with CD4094B
- These Devices are Pb-Free and are RoHS Compliant
- NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable

# ON

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#### **MARKING DIAGRAMS**



PDIP-16 P SUFFIX CASE 648 <sup>16</sup>**ሉሉሉሉሉሉሉ** MC14094BCP o AWLYYWWG 1**፲**፱፱፱፱፱፱፱፱



SOIC-16 D SUFFIX CASE 751B





TSSOP-16 DT SUFFIX CASE 948F





SOEIAJ-16 F SUFFIX CASE 966



A = Assembly Location

WL, L = Wafer Lot
YY, Y = Year
WW, W = Work Week
G or = Pb-Free Indicator

#### MAXIMUM RATINGS (Voltages Referenced to VSS)

Symbol	Parameter	Value	Unit
V <sub>DD</sub>	DC Supply Voltage Range	-0.5 to +18.0	V
V <sub>in</sub> , V <sub>out</sub>	Input or Output Voltage Range (DC or Transient)	-0.5 to V <sub>DD</sub> + 0.5	V
I <sub>in</sub> , I <sub>out</sub>	Input or Output Current (DC or Transient) per Pin	±10	mA
$P_{D}$	Power Dissipation, per Package (Note 1)	500	mW
T <sub>A</sub>	Ambient Temperature Range	-55 to +125	°C
T <sub>stg</sub>	Storage Temperature Range	-65 to +150	°C
TL	Lead Temperature (8–Second Soldering)	260	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. Temperature Derating: Plastic "P and D/DW" Packages: - 7.0 mW/°C From 65°C To 125°C

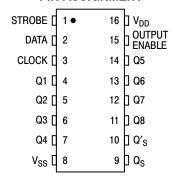
This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high–impedance circuit. For proper operation,  $V_{in}$  and  $V_{out}$  should be constrained to the range  $V_{SS} \leq (V_{in} \text{ or } V_{out}) \leq V_{DD}$ .

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either  $V_{SS}$  or  $V_{DD}$ ). Unused outputs must be left open.

#### **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

#### **PIN ASSIGNMENT**



#### **TRUTH TABLE**

	Output			Parallel Outputs		Serial Outputs	
Clock	Enable	Strobe	Data	Q1	Q <sub>N</sub>	Q <sub>S</sub> *	Q′s
	0	Х	Х	Z	Z	Q7	No Chg.
~	0	Х	Х	Z	Z	No Chg.	Q7
	1	0	Х	No Chg.	No Chg.	Q7	No Chg.
	1	1	0	0	Q <sub>N</sub> -1	Q7	No Chg.
	1	1	1	1	Q <sub>N</sub> -1	Q7	No Chg.
~	1	1	1	No Chg.	No Chg.	No Chg.	Q7

Z = High Impedance X = Don't Care

#### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
MC14094BCPG	PDIP-16 (Pb-Free)	500 Units / Rail
MC14094BDG	SOIC-16 (Pb-Free)	48 Units / Rail
MC14094BDR2G	SOIC-16	2500 Units / Tape & Reel
NLV14094BDR2G*	(Pb-Free)	
MC14094BDTR2G	TSSOP-16	2500 Units / Tape & Reel
NLV14094BDTR2G*	(Pb-Free)	
MC14094BFELG	SOEIAJ-16 (Pb-Free)	2000 Units / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

<sup>\*</sup> At the positive clock edge, information in the 7th shift register stage is transferred to Q8 and Qs.

<sup>\*</sup>NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable.

#### **ELECTRICAL CHARACTERISTICS** (Voltages Referenced to V<sub>SS</sub>)

		V <sub>DD</sub>	- 5	5°C		25°C		125	5°C	
Characteristic	Symbol	Vdc	Min	Max	Min	Typ <sup>(2)</sup>	Max	Min	Max	Unit
Output Voltage "0" I $V_{in} = V_{DD} \text{ or } 0$	evel V <sub>OL</sub>	5.0 10 15	- - -	0.05 0.05 0.05	- - -	0 0 0	0.05 0.05 0.05	- - -	0.05 0.05 0.05	Vdc
$V_{in} = 0 \text{ or } V_{DD}$ "1" I	evel V <sub>OH</sub>	5.0 10 15	4.95 9.95 14.95	- - -	4.95 9.95 14.95	5.0 10 15	- - -	4.95 9.95 14.95	- - -	Vdc
Input Voltage "0" I $(V_O = 4.5 \text{ or } 0.5 \text{ Vdc})$ $(V_O = 9.0 \text{ or } 1.0 \text{ Vdc})$ $(V_O = 13.5 \text{ or } 1.5 \text{ Vdc})$	evel V <sub>IL</sub>	5.0 10 15	- - -	1.5 3.0 4.0	- - -	2.25 4.50 6.75	1.5 3.0 4.0	- - -	1.5 3.0 4.0	Vdc
"1" $V_{O} = 0.5 \text{ or } 4.5 \text{ Vdc}$ ( $V_{O} = 1.0 \text{ or } 9.0 \text{ Vdc}$ ) ( $V_{O} = 1.5 \text{ or } 13.5 \text{ Vdc}$ )	evel V <sub>IH</sub>	5.0 10 15	3.5 7.0 11	- - -	3.5 7.0 11	2.75 5.50 8.25	- - -	3.5 7.0 11	- - -	Vdc
Output Drive Current $ (V_{OH} = 2.5 \text{ Vdc}) $ $ (V_{OH} = 4.6 \text{ Vdc}) $ $ (V_{OH} = 9.5 \text{ Vdc}) $ $ (V_{OH} = 13.5 \text{ Vdc}) $	urce I <sub>OH</sub>	5.0 5.0 10 15	- 3.0 - 0.64 - 1.6 - 4.2	- - -	- 2.4 - 0.51 - 1.3 - 3.4	- 4.2 - 0.88 - 2.25 - 8.8	- - -	- 1.7 - 0.36 - 0.9 - 2.4	- - -	mAdc
$(V_{OL} = 0.4 \text{ Vdc})$ $(V_{OL} = 0.5 \text{ Vdc})$ $(V_{OL} = 1.5 \text{ Vdc})$	Sink I <sub>OL</sub>	5.0 10 15	0.64 1.6 4.2	- - -	0.51 1.3 3.4	0.88 2.25 8.8	- - -	0.36 0.9 2.4	- - -	mAdc
Input Current	I <sub>in</sub>	15	-	±0.1	-	±0.00001	±0.1	-	±1.0	μAdc
Input Capacitance (V <sub>in</sub> = 0)	C <sub>in</sub>	-	-	-	-	5.0	7.5	-	-	pF
Quiescent Current (Per Package)	I <sub>DD</sub>	5.0 10 15	- - -	5.0 10 20	- - -	0.005 0.010 0.015	5.0 10 20	- - -	150 300 600	μAdc
Total Supply Current <sup>(3)</sup> <sup>(4)</sup> (Dynamic plus Quiescent, Per Package) (C <sub>L</sub> = 50 pF on all outputs, a buffers switching)	I <sub>T</sub>	5.0 10 15			$I_T = ($	I.1 μΑ/kHz) f 14 μΑ/kHz) f 40 μΑ/kHz) f	+ I <sub>DD</sub>			μAdc
3-State Output Leakage Curre	it I <sub>TL</sub>	15	-	±0.1	-	±0.0001	±0.1	_	±3.0	μΑ

Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.
 The formulas given are for the typical characteristics only at 25°C.
 To calculate total supply current at loads other than 50 pF:

$$I_T(C_L) = I_T(50 \text{ pF}) + (C_L - 50) \text{ Vfk}$$

where:  $I_T$  is in  $\mu A$  (per package),  $C_L$  in pF, V = ( $V_{DD} - V_{SS}$ ) in volts, f in kHz is input frequency, and k = 0.001.

### SWITCHING CHARACTERISTICS (5) ( $C_L$ = 50 pF, $T_A$ = 25°C)

Characteristic	Symbol	V <sub>DD</sub> Vdc	Min	Typ <sup>(6)</sup>	Max	Unit
Output Rise and Fall Time  t <sub>TLH</sub> , t <sub>THL</sub> = (1.35 ns/pF) C <sub>L</sub> + 33 ns  t <sub>TLH</sub> , t <sub>THL</sub> = (0.6 ns/pF) C <sub>L</sub> + 20 ns	t <sub>TLH</sub> , t <sub>THL</sub>	5.0 10		100 50	200 100	ns
$t_{TLH}$ , $t_{THL} = (0.6 \text{ Hs/pF}) C_L + 20 \text{ Hs}$ $t_{TLH}$ , $t_{THL} = (0.4 \text{ ns/pF}) C_L + 20 \text{ ns}$		15	_	40	80	
Propagation Delay Time (Figure 1) Clock to Serial out QS tplH, tpHL = (0.90 ns/pF) CL + 305 ns	t <sub>PLH</sub> , t <sub>PHL</sub>	5.0	_	350	600	ns
$t_{PLH}$ , $t_{PHL}$ = (0.36 ns/pF) $C_L$ + 107 ns $t_{PLH}$ , $t_{PHL}$ = (0.26 ns/pF) $C_L$ + 82 ns		10 15		125 95	250 190	
Clock to Serial out Q'S $t_{PLH}$ , $t_{PHL}$ = (0.90 ns/pF) $C_L$ + 350 ns $t_{PLH}$ , $t_{PHL}$ = (0.36 ns/pF) $C_L$ + 149 ns		5.0 10	_ _	230 110	460 220	
t <sub>PLH</sub> , t <sub>PHL</sub> = (0.26 ns/pF) C <sub>L</sub> + 62 ns		15	_	75	150	
Clock to Parallel out $t_{PLH}$ , $t_{PHL}$ = (0.90 ns/pF) $C_L$ + 375 ns $t_{PLH}$ , $t_{PHL}$ = (0.35 ns/pF) $C_L$ + 177 ns $t_{PLH}$ , $t_{PHL}$ = (0.26 ns/pF) $C_L$ + 122 ns		5.0 10 15	- - -	420 195 135	840 390 270	
Strobe to Parallel out $t_{PLH},t_{PHL}=(0.90\;\text{ns/pF})\;C_L+245\;\text{ns}\\t_{PLH},t_{PHL}=(0.36\;\text{ns/pF})\;C\;L+127\;\text{ns}\\t_{PLH},t_{PHL}=(0.26\;\text{ns/pF})\;C_L+87\;\text{ns}$		5.0 10 15	- - -	290 145 100	580 290 200	
Output Enable to Output $t_{PHZ},t_{PZL}=(0.90\;\text{ns/pF})\;C_L+95\;\text{ns}\\t_{PHZ},t_{PZL}=(0.36\;\text{ns/PF})\;C_L+57\;\text{ns}\\t_{PHZ},t_{PZL}=(0.26\;\text{ns/pF})\;C_L+42\;\text{ns}$	t <sub>PHZ</sub> , t <sub>PZL</sub>	5.0 10 15	- - -	140 75 55	280 150 110	
$\begin{array}{l} t_{PLZ},t_{PZH} = (0.90\;\text{ns/pF})\;C_L + 180\;\text{ns} \\ t_{PLZ},t_{PZH} = (0.36\;\text{ns/pF})\;C_L + 77\;\text{ns} \\ t_{PLZ},t_{PZH} = (0.26\;\text{ns/pF})\;C_L + 57\;\text{ns} \end{array}$	t <sub>PLZ</sub> , t <sub>PZH</sub>	5.0 10 15	- - -	225 95 70	450 190 140	
Setup Time Data in to Clock	t <sub>su</sub>	5.0 10 15	125 55 35	60 30 20	- - -	ns
Hold Time Clock to Data	t <sub>h</sub>	5.0 10 15	0 20 20	- 40 - 10 0	- - -	ns
Clock Pulse Width, High	t <sub>WH</sub>	5.0 10 15	200 100 83	100 50 40	- - -	ns
Clock Rise and Fall Time	t <sub>r(Cl)</sub>	5 10 15	- - -	_ _ _	15 5.0 4.0	μs
Clock Pulse Frequency	f <sub>cl</sub>	5.0 10 15	- - -	2.5 5.0 6.0	1.25 2.5 3.0	MHz
Strobe Pulse Width	t <sub>WL</sub>	5.0 10 15	200 80 70	100 40 35	- - -	ns

<sup>5.</sup> The formulas given are for the typical characteristics only at 25°C.
6. Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.

#### **3-STATE TEST CIRCUIT**

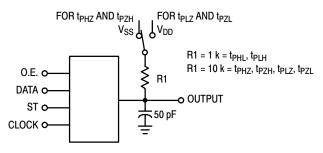
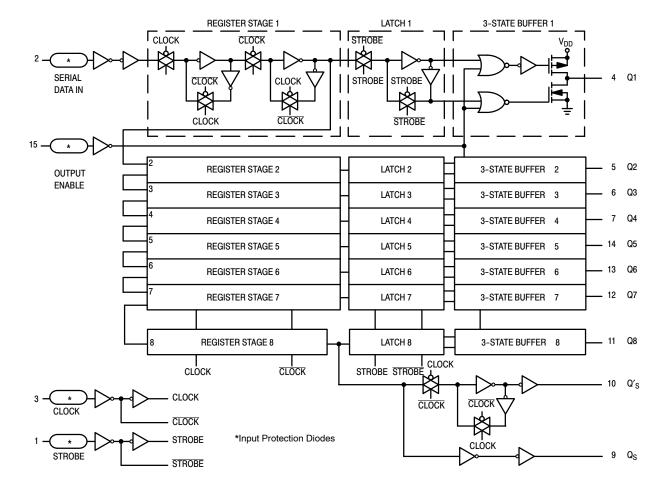
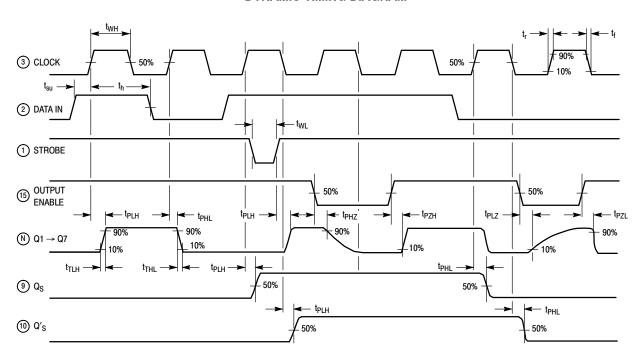


Figure 1.

#### **BLOCK DIAGRAM**

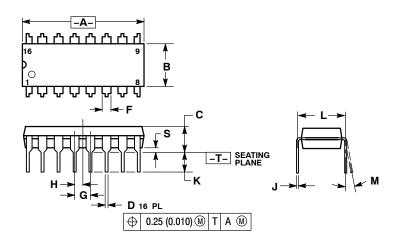


#### **DYNAMIC TIMING DIAGRAM**



#### **PACKAGE DIMENSIONS**

PDIP-16 **P SUFFIX** CASE 648-08 **ISSUE T** 

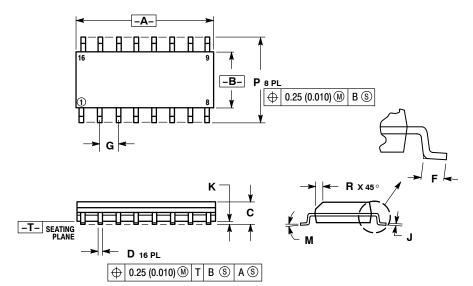


- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.
  3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
  4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
  5. ROUNDED CORNERS OPTIONAL.

	INC	HES	MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.740	0.770	18.80	19.55
В	0.250	0.270	6.35	6.85
С	0.145	0.175	3.69	4.44
D	0.015	0.021	0.39	0.53
F	0.040	0.70	1.02	1.77
G	0.100	BSC	2.54	BSC
Н	0.050	BSC	1.27 BSC	
J	0.008	0.015	0.21	0.38
K	0.110	0.130	2.80	3.30
L	0.295	0.305	7.50	7.74
М	0°	10 °	0 °	10 °
S	0.020	0.040	0.51	1.01

#### **PACKAGE DIMENSIONS**

SOIC-16 **D SUFFIX** CASE 751B-05 ISSUE K



- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: MILLIMETER.
  3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTEINSION.
- PROTRUSION.

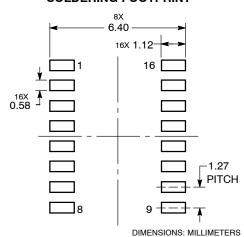
  MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.

  DIMENSION D DOES NOT INCLUDE DAMBAR

  PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIN	IETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	9.80	10.00	0.386	0.393
В	3.80	4.00	0.150	0.157
С	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27	BSC	0.050 BSC	
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0 °	7°	0°	7°
P	5.80	6.20	0.229	0.244
R	0.25	0.50	0.010	0.019

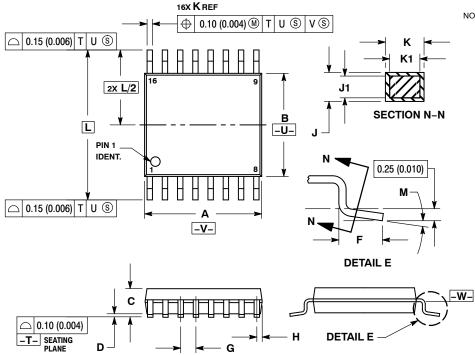
#### **SOLDERING FOOTPRINT\***



\*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

#### **PACKAGE DIMENSIONS**

#### TSSOP-16 **DT SUFFIX** CASE 948F-01 **ISSUE B**



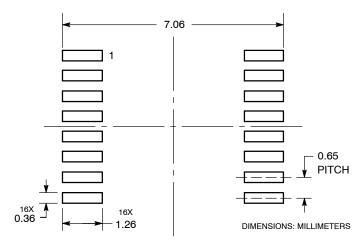
#### NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- 2. CONTROLLING DIMENSION: MILLIMETER.
  3. DIMENSION A DOES NOT INCLUDE MOLD FLASH. PROTRUSIONS OR GATE BURRS.
- MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.

  4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
- 5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION. ALLOWABLE
  DAMBAR PROTRUSION SHALL BE 0.08
  (0.003) TOTAL IN EXCESS OF THE K
  DIMENSION AT MAXIMUM MATERIAL
  CONDITION.
- 6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
  7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

	MILLIN	IETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	4.90	5.10	0.193	0.200
В	4.30	4.50	0.169	0.177
C		1.20		0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65	BSC	0.026 BSC	
Н	0.18	0.28	0.007	0.011
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252	BSC
М	0°	8 °	0°	8 °

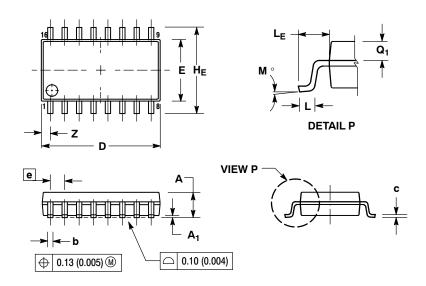
#### **SOLDERING FOOTPRINT\***



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

#### PACKAGE DIMENSIONS

SOEIAJ-16 **F SUFFIX** CASE 966-01 **ISSUE A** 



#### NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: MILLIMETER.
- B. DIMENSIONS D AND E DO NOT INCLUDE
  MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
- TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
- i. THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION.

  DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 ( 0.018).

	MILLIN	IETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α		2.05		0.081
A <sub>1</sub>	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
С	0.10	0.20	0.007	0.011
D	9.90	10.50	0.390	0.413
Е	5.10	5.45	0.201	0.215
е	1.27	BSC	0.050 BSC	
HE	7.40	8.20	0.291	0.323
L	0.50	0.85	0.020	0.033
LE	1.10	1.50	0.043	0.059
M	0 °	10 °	0 °	10°
Q <sub>1</sub>	0.70	0.90	0.028	0.035
Z		0.78		0.031

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